

# Top & Bottom Grinder for multi-ingots

LOG-O-MATIC®



## Features

Special development for multi-crystalline silicon ingots

- High output with low cost
- Significant material waste reduction
- Less risk of wire breakage for squaring
- Flat surfaces for further processing
- Save up to 3 % cost of wafer manufacturing
- Mechanical clamping
- Automatic grinding process

## Capacity

- 4 – 5 ingots / day
- 77 MW

## Technical data

Layout	approx. 3 m x 2.2 m
Height	max. 2.6 m
Weight	approx. 5,000 kg
Ingot clamping	mechanical
Max. in-feed	75 mm
Grinding wheel	diamond wheel
Diameter	610 mm / 720 mm
Rotary table	
Speed	variable
Work piece diameter	1,100 mm
Coolant water	max. 1,200 l / h
El. connection	15 kVA
Software	Siemens CNC S7



Ingot

- Remeltable material
- Dirt, to be discarded